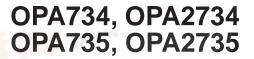


Burr-Brown Products from Texas Instruments

查询"OPA734"供应商





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0.05µV/°C max, SINGLE-SUPPLY CMOS OPERATIONAL AMPLIFIERS Zer∞-Drift Series

FEATURES

- LOW OFFSET VOLTAGE: 5µV (max)
- ZERO DRIFT: 0.05µV/°C max
- QUIESCENT CURRENT: 750μA (max)
- SINGLE-SUPPLY OPERATION
- LOW BIAS CURRENT: 200pA (max)
- SHUTDOWN
- MicroSIZE PACKAGES
- WIDE SUPPLY RANGE: 2.7V to 12V

APPLICATIONS

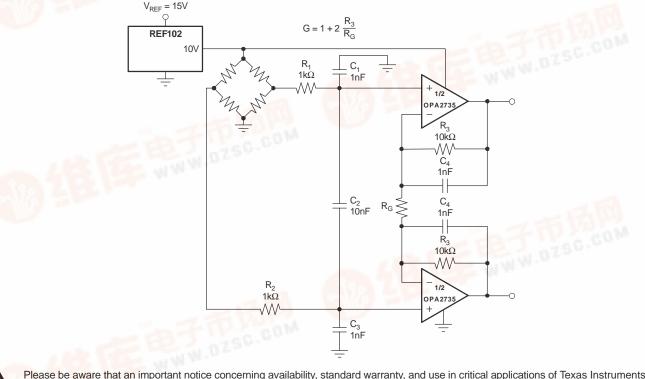
- TRANSDUCER APPLICATIONS
- TEMPERATURE MEASUREMENTS
- ELECTRONIC SCALES
- MEDICAL INSTRUMENTATION
- BATTERY-POWERED INSTRUMENTS
- HANDHELD TEST EQUIPMENT

DESCRIPTION

The OPA734 and OPA735 series of CMOS operational amplifiers use auto-zeroing techniques to simultaneously provide low offset voltage (5μ V max) and near-zero drift over time and temperature. These miniature, high-precision, low quiescent current amplifiers offer high input impedance and rail-to-rail output swing within 50mV of the rails. Either single or bipolar supplies can be used in the range of +2.7V to +12V (±1.35V to ±6V). They are optimized for low-voltage, single-supply operation.

The OPA734 family includes a shutdown mode. Under logic control, the amplifiers can be switched from normal operation to a standby current that is 9μ A (max) and the output placed in a high-impedance state.

The single version is available in the MicroSIZE SOT23-5 (SOT23-6 for shutdown version) and the SO-8 packages. The dual version is available in the MSOP-8 and SO-8 packages (MSOP-10 only for the shutdown version). All versions are specified for operation from -40° C to $+85^{\circ}$ C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. roduction processing does not necessarily include testing of all parameters.

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage +13.2V
Signal Input Terminals, Voltage ⁽²⁾ (V–) – 0.5V to (V+) + 0.5V
Current ⁽²⁾ ±10mA
Output Short Circuit ⁽³⁾ Continuous
Operating Temperature40°C to +150°C
Storage Temperature
Junction Temperature
Lead Temperature (soldering, 10s) +300°C
ESD Rating (Human Body Model), OPA734 1000V
ESD Rating (Human Body Model), OPA735, OPA2734, OPA2735 2000V

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground, one amplifier per package.

PACKAGE/ORDERING INFORMATION⁽¹⁾



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

RUMENTS www.ti.com

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
Shutdown Version						
OPA734	SOT23-6	DBV	-40°C to +85°C	NSB	OPA734AIDBVT	Tape and Reel, 250
"	"	"	"	"	OPA734AIDBVR	Tape and Reel, 3000
OPA734	SO-8	D	-40°C to +85°C	OPA734A	OPA734AID	Rails, 100
"	"	"	"	"	OPA734AIDR	Tape and Reel, 2500
OPA2734	MSOP-10	DGS	-40°C to +85°C	BGO	OPA2734AIDGST	Tape and Reel, 250
"	"	"	"	"	OPA2734AIDGSR	Tape and Reel, 2500
Non-Shutdown Version						
OPA735	SOT23-5	DBV	-40°C to +85°C	NSC	OPA735AIDBVT	Tape and Reel, 250
"	"	"	"	"	OPA735AIDBVR	Tape and Reel, 3000
OPA735	SO-8	D	-40°C to +85°C	OPA735A	OPA735AID	Rails, 100
"	"	"	"	"	OPA735AIDR	Tape and Reel, 2500
OPA2735	SO-8	D	-40°C to +85°C	OPA2735A	OPA2735AID	Rails, 100
"	"	"	"	"	OPA2735AIDR	Tape and Reel, 2500
OPA2735	MSOP-8	DGK	-40°C to +85°C	BGN	OPA2735AIDGKT	Tape and Reel, 250
"	"	"	"	"	OPA2735AIDGKR	Tape and Reel, 2500

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ELECTRICAL CHARACTERISTICS: $V_S = \pm 5V$ ($V_S = +10V$) Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

At $T_A = +25^{\circ}C$, $R_L = 10k\Omega$ connected to $V_S/2$, and $V_{OUT} = V_S/2$, unless otherwise noted.

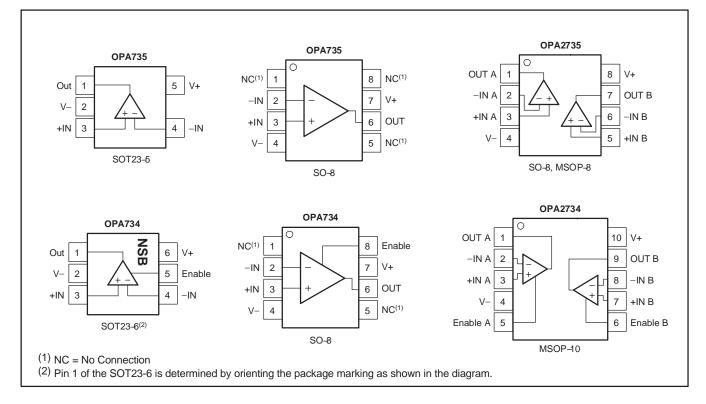
			OPA734, O	PA2734, OPA73	5, OPA2735	1
PARAMETER		CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET VOLTAGE						
Input Offset Voltage	Vos			1	5	μV
vs Temperature	dV _{OS} /dT			0.01	0.05	μ ν/ °C
vs Power Supply	PSRR	V _S = 2.7V to 12V, V _{CM} = 0V		0.2	1.8	μ V/V
Long-Term Stability		• •		Note (1)		
Channel Separation, dc				0.1		μV/V
INPUT BIAS CURRENT						
Input Bias Current	IВ	$V_{CM} = V_S/2$		±100	±200	pА
over Temperature	D		See T	vpical Characte	ristics	pA
Input Offset Current	los	$V_{CM} = V_S/2$		±200	±300	рА
NOISE						
Input Voltage Noise, $f = 0.01Hz$ to 1Hz	e _n			0.8		μVpp
Input Voltage Noise, $f = 0.1Hz$ to 10Hz	en			2.5		μVpp
Input Voltage Noise Density, f = 1kHz	en			135		nV/√Hz
Input Current Noise Density, f = 1kHz	in			40		fA/√Hz
INPUT VOLTAGE RANGE						
Common-Mode Voltage Range	Vсм		(V–) – 0.1		(V+) – 1.5	v
Common-Mode Rejection Ratio	CMRR	(V−) − 0.1V < V _{CM} < (V+) − 1.5V	115	130		dB
Differential				2		pF
Common-Mode				10		pF
OPEN-LOOP GAIN				-		+ '
Open-Loop Voltage Gain	AOL	(V–) + 100mV < V _O < (V+) – 100mV	115	130		dB
FREQUENCY RESPONSE	02	., .,				
Gain-Bandwidth Product	GBW			1.6		MHz
Slew Rate	SR	G = +1		1.5		V/µs
OUTPUT						· ·
Voltage Output Swing from Rail		RL = 10kΩ		20	50	mV
Short-Circuit Current	ISC			±20		mA
Open-Loop Output Impedance	.30	$f = 1MHz, I_{O} = 0$		125		Ω
Capacitive Load Drive	C _{LOAD}	1 = 111112, 10 = 0	See -	Typical Character	ristics	
ENABLE/SHUTDOWN	LOAD			51		
tOFF				1.5		μs
ton ⁽²⁾				150		μs
V _I (amplifier is shutdown)	1		V-		(V–) + 0.8	V
V _H (amplifier is active)			(V–) + 2		V+	V
IQSD (per amplifier)			· · ·	4	9	μA
Input Bias Current of Enable Pin				3	-	μA
POWER SUPPLY						1
Operating Voltage Range	Vs			2.7 to 12		V
Quiescent Current (per amplifier)	lq	l _O = 0		(±1.35 to ±6) 0.6	0.75	mA
TEMPERATURE RANGE	·u	-0 - •				1
Specified Range			-40		+85	°C
Operating Range			-40		+150	°C
Storage Range			-65		+150	°C
Thermal Resistance	ALA		-00		1100	°C/W
	θ_{JA}			200		°C/W
SOT23-5, SOT23-6						

(1) 300-hour life test at 150°C demonstrated randomly distributed variation in the range of measurement limits—approximately 1µV.

(2) Device requires one complete auto-zero cycle to return to VOS accuracy.



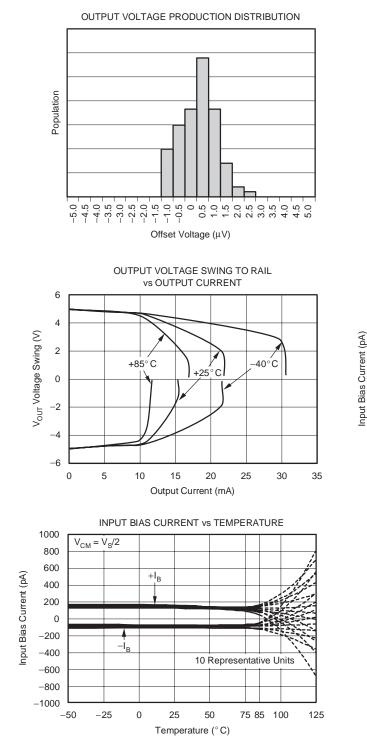
PIN CONFIGURATIONS



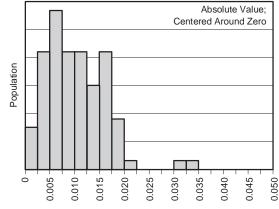


TYPICAL CHARACTERISTICS

At $T_A = +25^{\circ}C$, $V_S = \pm 5V$ (same as +10V).

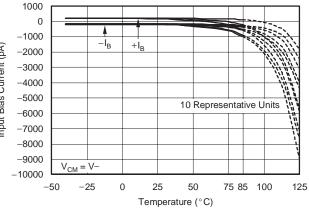


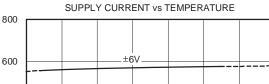
OUTPUT VOLTAGE DRIFT PRODUCTION DISTRIBUTION

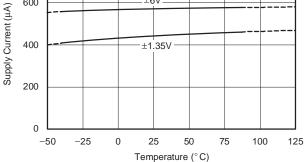


Offset Voltage Drift (µV/°C)







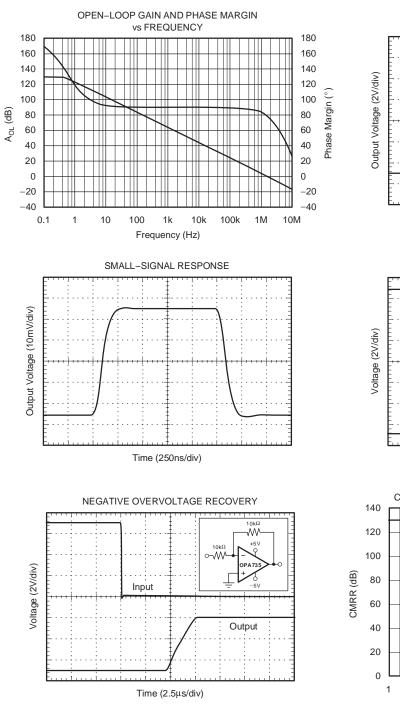


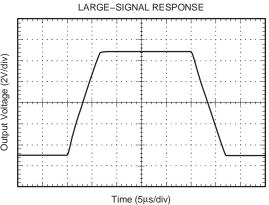
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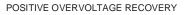
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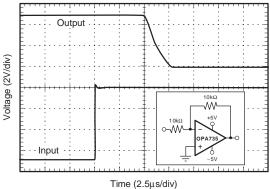
TYPICAL CHARACTERISTICS (continued)

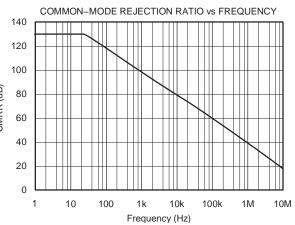
At $T_A = +25^{\circ}C$, $V_S = \pm 5V$ (same as +10V).

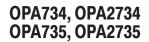










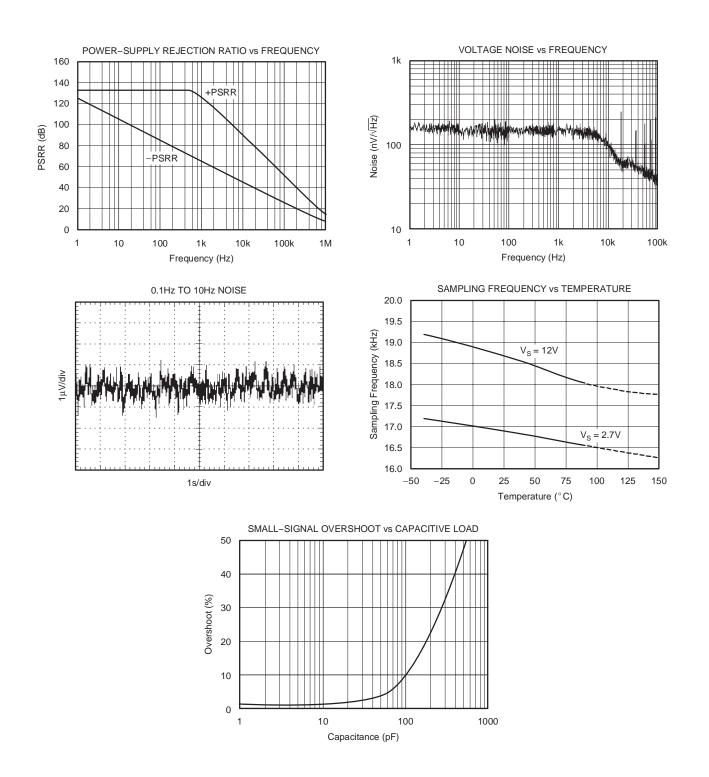


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TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, V_S = \pm 5V (same as +10V).



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APPLICATIONS INFORMATION

The OPA734 and OPA735 series of op amps are unity-gain stable and free from unexpected output phase reversal. They use auto-zeroing techniques to provide low offset voltage and demonstrate very low drift over time and temperature.

Good layout practice mandates the use of a $0.1 \mu F$ capacitor placed closely across the supply pins.

For lowest offset voltage and precision performance, circuit layout and mechanical conditions should be optimized. Avoid temperature gradients that create thermoelectric (Seebeck) effects in thermocouple junctions formed from connecting dissimilar conductors. These thermally-generated potentials can be made to cancel by assuring that they are equal on both input terminals:

- 1. Use low thermoelectric-coefficient connections (avoid dissimilar metals).
- 2. Thermally isolate components from power supplies or other heat sources.
- 3. Shield op amp and input circuitry from air currents such as cooling fans.

Following these guidelines will reduce the likelihood of junctions being at different temperatures, which can cause thermoelectric voltages of $0.1 \mu V/^{\circ}C$ or higher, depending on the materials used.

OPERATING VOLTAGE

The OPA734 and OPA735 op amp family operates with a power-supply range of +2.7V to +12V (\pm 1.35V to \pm 6V). Supply voltages higher than +13.2V (absolute maximum) can permanently damage the amplifier. Parameters that vary over supply voltage or temperature are shown in the Typical Characteristics section of this data sheet.

OPA734 ENABLE FUNCTION

The enable/shutdown digital input is referenced to the V– supply voltage of the op amp. A logic HIGH enables the op amp. A valid logic HIGH is defined as > (V-) + 2V. The valid logic HIGH signal can be up to the positive supply, independent of the negative power supply voltage. A valid logic LOW is defined as < 0.8V above the V– supply pin. If dual or split power supplies are used, be sure that logic input signals are properly referred to the negative supply voltage. The Enable pin is connected to internal pull-up circuitry and will enable the device if this pin is left open circuit. The logic input is a CMOS input. Separate logic inputs are provided for each op amp on the dual version. For battery-operated applications, this feature can be used to greatly reduce the average current and extend battery life.

RUMENTS

The enable time is 150μ s, which includes one full auto-zero cycle required by the amplifier to return to V_{OS} accuracy. Prior to returning to full accuracy, the amplifier may function properly, but with unspecified offset voltage.

Disable time is 1.5μ s. When disabled, the output assumes a high-impedance state. The disable state allows the OPA734 to be operated as a gated amplifier, or to have the output multiplexed onto a common analog output bus.

INPUT VOLTAGE

The input common-mode range extends from (V-) - 0.1V to (V+) - 1.5V. For normal operation, the inputs must be limited to this range. The common-mode rejection ratio is only valid within the specified input common-mode range. A lower supply voltage results in lower input common-mode range; therefore, attention to these values must be given when selecting the input bias voltage. For example, when operating on a single 3V power supply, common-mode range is from 0.1V below ground to half the power-supply voltage.

Normally, input bias current is approximately 100pA; however, input voltages exceeding the power supplies can cause excessive current to flow in or out of the input pins. Momentary voltages greater than the power supply can be tolerated if the input current is limited to 10mA. This is easily accomplished with an input resistor, as shown in Figure 1.

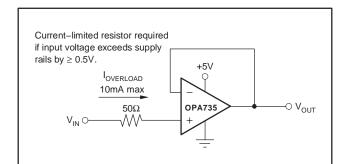


Figure 1. Input Current Protection

INTERNAL OFFSET CORRECTION

The OPA734 and OPA735 series of op amps use an auto-zero topology with a time-continuous 1.6MHz op amp in the signal path. This amplifier is zero-corrected every 100 μ s using a proprietary technique. Upon power-up, the amplifier requires one full auto-zero cycle of approximately 100 μ s in addition to the start-up time for the bias circuitry to achieve specified V_{OS} accuracy. Prior to this time, the amplifier may function properly but with unspecified offset voltage.



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Low-gain (< 20) operation demands that the auto-zero circuitry correct for common-mode rejection errors of the main amplifier. Because these errors can be larger than 0.1% of a full-scale input step change, one calibration cycle (100μ s) can be required to achieve full accuracy.

The term *clock* feedthrough describes the presence of the clock frequency in the output spectrum. In auto-zeroed op amps, clock feedthrough may result from the settling of the internal sampling capacitor, or from the small amount of charge injection that occurs during the sample-and-hold of the op amp offset voltage. Feedthrough can be minimized by keeping the source impedance relatively low (< 1k Ω) and matching the source resistance is high (> 1k Ω) feedthrough can generally be reduced with a capacitor of 1nF or greater in parallel with the source or feedback resistors. See the circuit application examples.

LAYOUT GUIDELINES

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1μ F capacitor closely across the supply pins. These guidelines should be applied throughout the analog circuit to improve performance and provide benefits such as reducing the electromagnetic-interference (EMI) susceptibility.

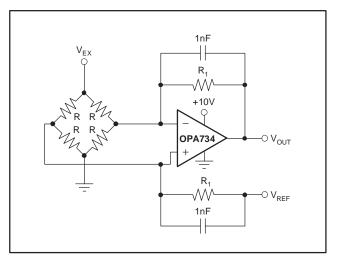


Figure 2. Single Op Amp Bridge Amplifier Circuit

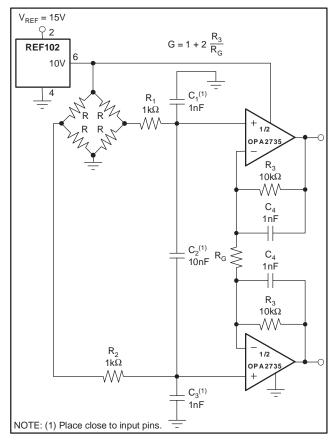


Figure 3. Differential Output Bridge Amplifier



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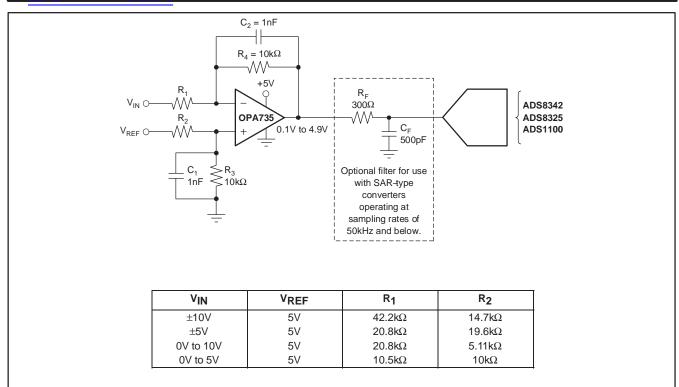
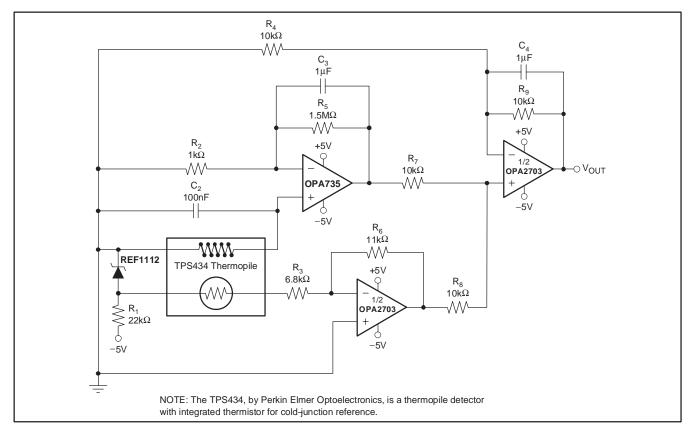
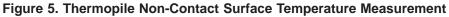


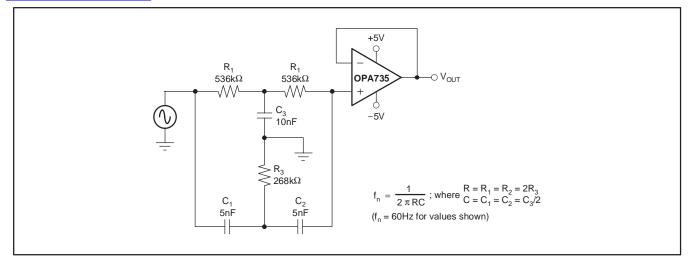
Figure 4. Driving ADC



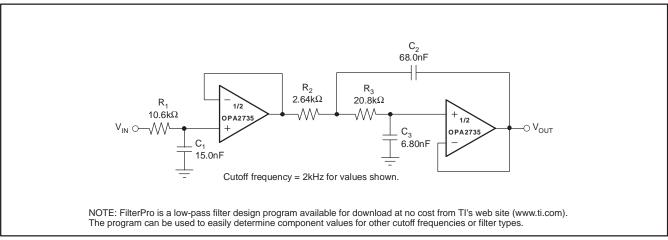


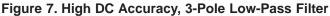


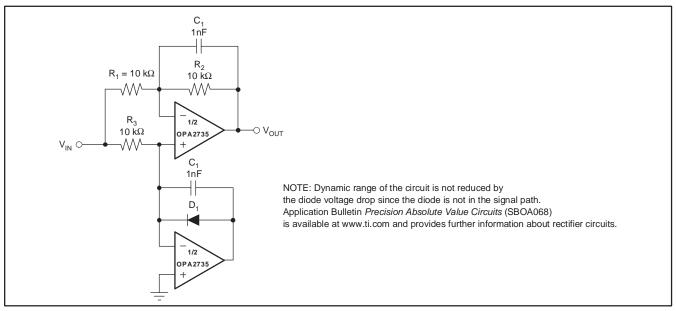
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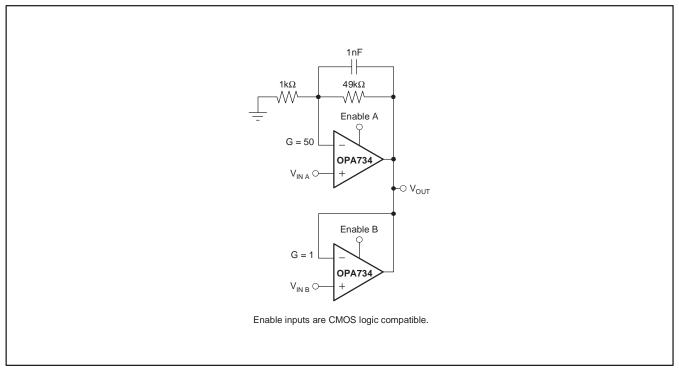


Figure 9. High-Precision 2-Input MUX for Programmable Gain

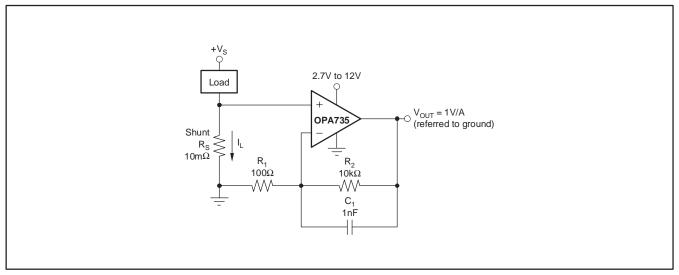


Figure 10. Low-Side Power-Supply Current Sensing

PACKAG



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pe
OPA2734AIDGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2734AIDGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2734AIDGST	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2734AIDGSTG4	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA2735AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA734AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA734AIDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA734AIDBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA734AIDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA734AIDBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
						& 110 SD/DT)		



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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pe
OPA734AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260
OPA735AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www. information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retard

in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

PACKAG



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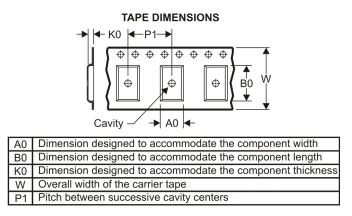
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2734AIDGSR	MSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2734AIDGST	MSOP	DGS	10	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2735AIDGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2735AIDGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2735AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA734AIDBVR	SOT-23	DBV	6	3000	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA734AIDBVT	SOT-23	DBV	6	250	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA735AIDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA735AIDBVT	SOT-23	DBV	5	250	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA735AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

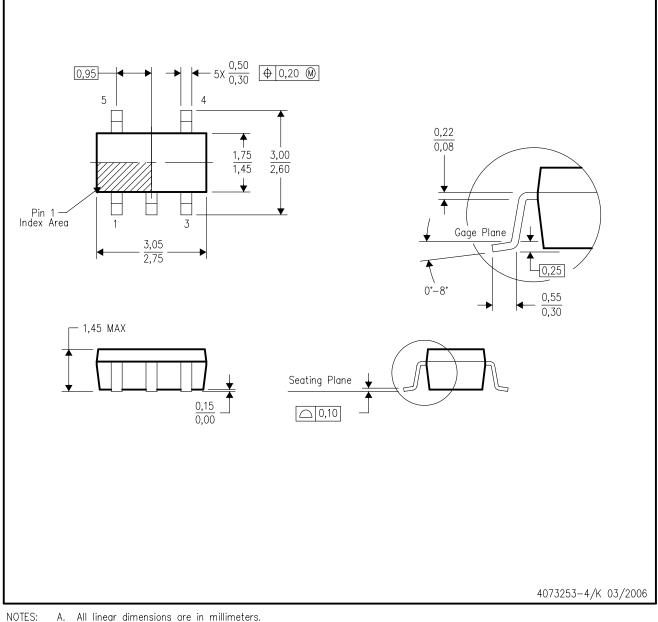
23-Jul-2010



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2734AIDGSR	MSOP	DGS	10	2500	346.0	346.0	29.0
OPA2734AIDGST	MSOP	DGS	10	250	190.5	212.7	31.8
OPA2735AIDGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
OPA2735AIDGKT	MSOP	DGK	8	250	190.5	212.7	31.8
OPA2735AIDR	SOIC	D	8	2500	346.0	346.0	29.0
OPA734AIDBVR	SOT-23	DBV	6	3000	190.5	212.7	31.8
OPA734AIDBVT	SOT-23	DBV	6	250	190.5	212.7	31.8
OPA735AIDBVR	SOT-23	DBV	5	3000	190.5	212.7	31.8
OPA735AIDBVT	SOT-23	DBV	5	250	190.5	212.7	31.8
OPA735AIDR	SOIC	D	8	2500	346.0	346.0	29.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



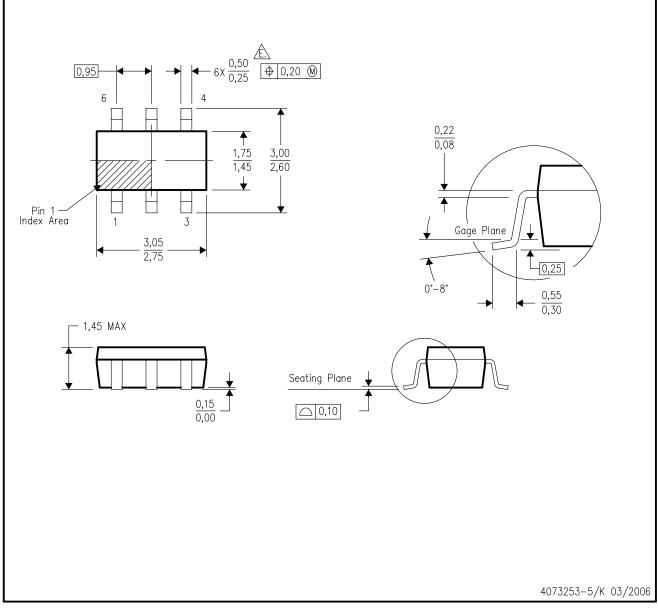
Α. All linear dimensions are in millimeters.

- Β. This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side. C.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

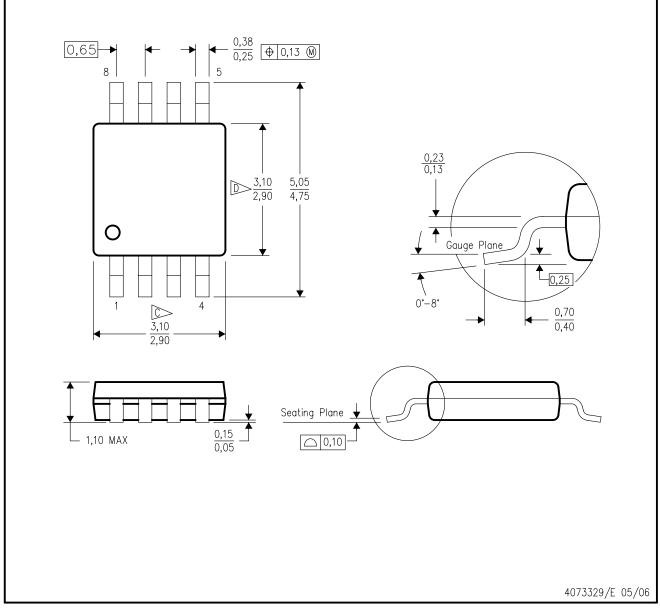


- NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- È. Falls within JEDEC MO-178 Variation AB, except minimum lead width.



DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

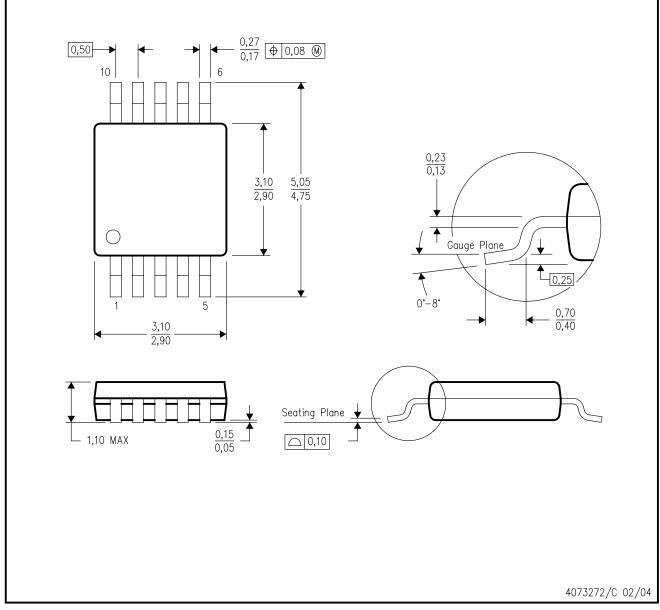
Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.

- D Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

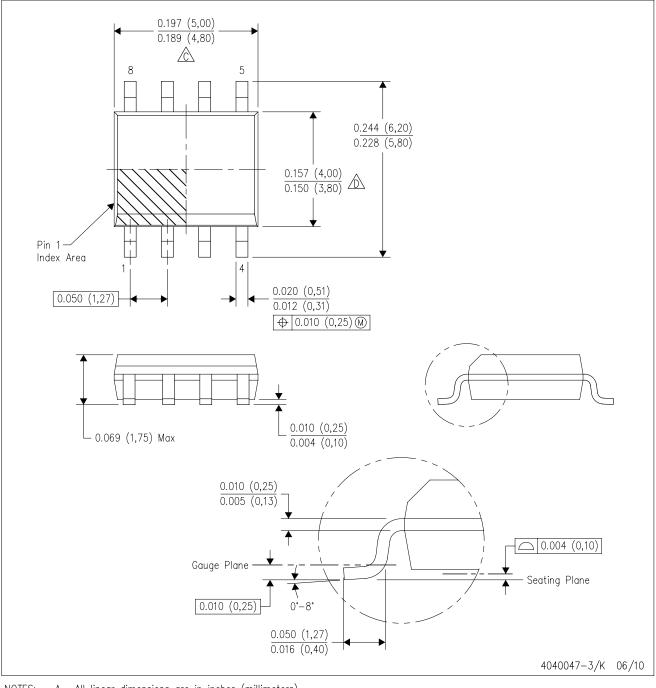
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation BA.



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D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



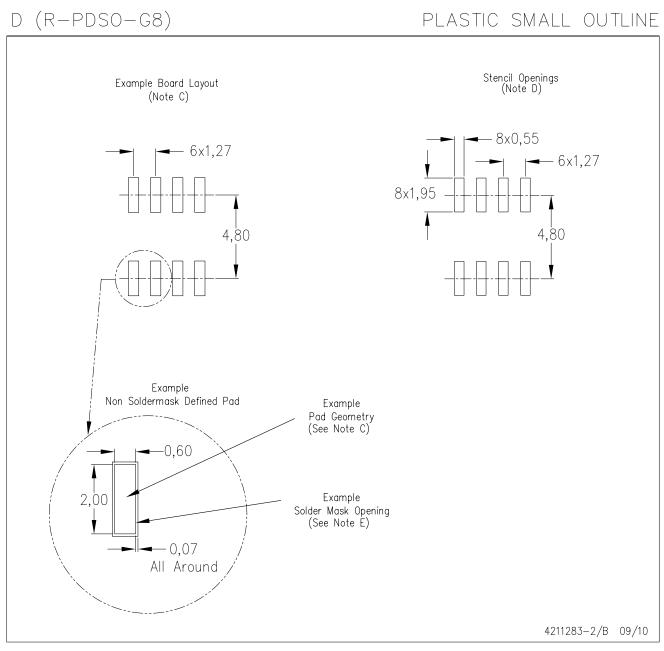
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



LAND PATTERN DATA

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NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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